



AP2112

Description

The AP2112 is CMOS process low dropout linear regulator with enable function, the regulator delivers a guaranteed 600mA (min.) continuous load current.

The AP2112 is available with a fixed output voltage of 1.2V, 1.8V, 2.5V, 2.6V, or 3.3V. The LDO has an output accuracy of \pm 1.5% and a very fast loop response providing excellent performance for dealing with line and load transients. The AP2112 includes an auto discharge function which connects the output to ground via 60 Ω of resistance when the device is disabled.

The regulator features low power consumption, and provides SOT25, SOT89-5, and SO-8 packages. Previously SOT-23-5, SOT-89-5 and SOIC-8 packages were respectively identified as SOT23-5, SOT89-5 and SO-8 but have been renamed to match the latest Diodes Incorporated's nomenclature.

Features

- Output Voltage Accuracy: ±1.5%
- Output Current: 600mA (Min.)
- Foldback Short Current Protection: 50mA
- Enable Function to Turn ON/OFF VOUT
- Low Dropout Voltage (3.3V): 250mV (Typ.) @I_{OUT} = 600mA
- Excellent Load Regulation: 0.2%/A (Typ.)
- Excellent Line Regulation: 0.02%/V (Typ.)
- Low Quiescent Current: 55µA (Typ.)
- Low Standby Current: 0.01µA (Typ.)
- Low Output Noise: 50µV_{RMS}
- PSRR: 100Hz -65dB, 1kHz -65dB
- OTSD Protection
- Stable with 1.0µF Flexible Cap: Ceramic, Tantalum and Aluminum Electrolytic
- Operation Temperature Range: -40°C to +85°C
- ESD: MM 400V, HBM 4000V
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Applications

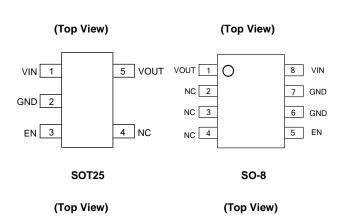
- Laptop Computer
- LCD Monitor
- Portable DVD

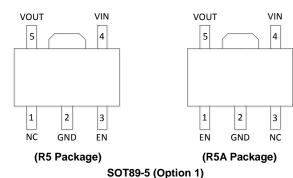
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

600mA CMOS LDO REGULATOR WITH ENABLE

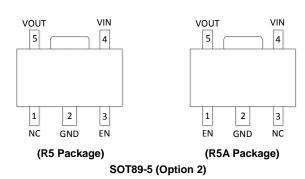
Pin Assignments





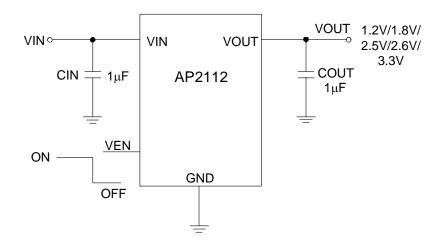
(Top View)

(Top View)





Typical Applications Circuit (Note 4)

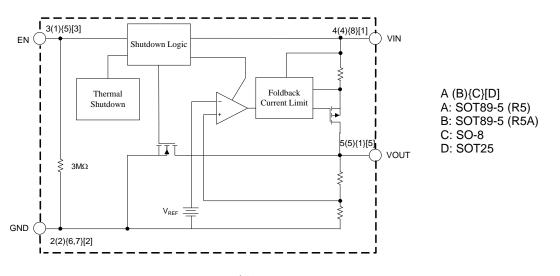


Note 4: It is recommended to use X7R or X5R dielectric capacitor if 1.0µF ceramic capacitor is selected as input/output capacitors.

Pin Descriptions

	Pin Number		Die Neue	F actoria
SOT25	SOT89-5	SO-8	Pin Name	Function
1	4	8	VIN	Input Voltage
2	2	6, 7	GND	GND
	3 (R5)	_		
3	1 (R5A)	5	EN	Chip Enable, H – normal work, L – shutdown output
	1 (R5)			
_	3 (R5A)	2, 3, 4	NC	No Connection
5	5	1	VOUT	Output Voltage

Functional Block Diagram





Absolute Maximum Ratings (Note 5)

Symbol	Parameter	Rating		Unit
Vcc	Power Supply Voltage	6.	5	V
TJ	Operating Junction Temperature Range	+1	50	°C
T _{STG}	Storage Temperature Range	-65 to	+150	°C
T _{LEAD}	Lead Temperature (Soldering, 10 Seconds)	+260		°C
		SOT25	184	
θ _{JA}	Thermal Resistance (Junction to Ambient)(No Heatsink)	SO-8	114	°C/W
		SOT89-5	120	
_	ESD (Machine Model)	40	400	
_	ESD (Human Body Model)	4000		V

Note 5: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Min	Мах	Unit
V _{IN}	Supply Voltage	2.5	6.0	V
T _A	Ambient Operation Temperature Range	-40	+85	°C



Electrical Characteristics

AP2112-1.2 Electrical Characteristics ($@V_{IN} = 2.5V$, $C_{IN} = 1.0\mu F$ (Ceramic), $C_{OUT} = 1.0\mu F$ (Ceramic), Typical $T_A = +25^{\circ}C$, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ons	Min	Тур	Max	Unit
Vout	Output Voltage	$V_{IN} = 2.5V$, 1mA $\leq I_C$	ou⊤ ≤ 30mA	V _{ОUT} *98.5%	1.2	V _{OUT} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	$V_{IN} = 2.5V, V_{OUT} = 1$.182V to 1.218V	600	_	_	mA
$(\Delta V_{OUT}/V_{OUT})/\Delta I_{OUT}$	Load Regulation	$V_{IN} = 2.5V, 1mA \le I_C$	_{0UT} ≤ 600mA	-1	0.2	1	%/A
(ΔVout/Vout)/ΔVin	Line Regulation	$2.5V \le V_{IN} \le 6V, I_{OU}$	⊤ = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	1000	1300	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA			1000	1300	mV
		I _{OUT} = 600mA		_	1000	1300	
Ι _Q	Quiescent Current	$V_{IN} = 2.5V, I_{OUT} = 0n$	nA	_	55	80	μA
I _{STD}	Standby Current	$V_{IN} = 2.5V, V_{EN}$ in O	FF mode	_	0.01	1.0	μA
		Ripple 0.5Vp-p	f = 100Hz	_	65	_	
PSRR	Power Supply Rejection Ratio	V _{IN} = 2.5V, I _{OUT} = 100mA	f = 1kHz	_	65	_	dB
(ΔVουτ/Vουτ)/ΔΤ	Output Voltage Temperature Coefficient	I _{OUT} = 30mA T _A = -40°C to +85°C		_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	V _{OUT} = 0V		_	50	—	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	—	μV _{RMS}
VIH	V _{EN} High Voltage	Enable logic high, re	gulator on	1.5	_	6.0	
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0	_	0.4	V
t _S	Start-up Time	No Load		_	20	—	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	MΩ
RDCHG	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	_	
T _{HYOTSD}	Thermal Shutdown Hysteresis	_		—	+25	_	°C
		SOT25		_	96	_	
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		—	75	_	°C/W
		SOT89-5		_	47	_	



AP2112-1.8 Electrical Characteristics ($@V_{IN} = 2.8V$, $C_{IN} = 1.0\mu F$ (Ceramic), $C_{OUT} = 1.0\mu F$ (Ceramic), Typical $T_A = +25^{\circ}C$, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ions	Min	Тур	Max	Unit
Vout	Output Voltage	$V_{IN} = 2.8V$, 1mA $\leq I_C$	00T ≤ 30mA	V _{ОUТ} *98.5%	1.8	V _{ОUT} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	$V_{IN} = 2.8V, V_{OUT} = 1$.773V to 1.827V	600	_	—	mA
(ΔVουτ/Vουτ)/ΔΙουτ	Load Regulation	$V_{OUT} = 1.8V, V_{IN} = V$ 1mA $\leq I_{OUT} \leq 600mA$		-1	0.2	1	%/A
$(\Delta V_{OUT}/V_{OUT})/\Delta V_{IN}$	Line Regulation	$2.8V \le V_{IN} \le 6V, I_{OU}$	_T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		—	500	700	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		—	500	700	mV
		I _{OUT} = 600mA		_	500	700	
Ι _Q	Quiescent Current	$V_{IN} = 2.8V, I_{OUT} = 0r$	nA	_	55	80	μA
I _{STD}	Standby Current	V_{IN} = 2.8V, V_{EN} in O	FF mode	_	0.01	1.0	μA
		Ripple 0.5Vp-p V _{IN} = 2.8V,	f = 100Hz	_	65	_	
PSRR	PSRR Power Supply Rejection Ratio		f = 1kHz	_	65	_	dB
(ΔV _{OUT} /V _{OUT})/ΔT	Output Voltage Temperature Coefficient	I _{OUT} = 30mA T _A = -40°C to +85°C	;	_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	$V_{OUT} = 0V$		—	50	—	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	—	μV _{RMS}
V _{IH}	V _{EN} High Voltage	Enable logic high, re	egulator on	1.5	_	6.0	V
VIL	V _{EN} Low Voltage	Enable logic low, reo	gulator off	0	_	0.4	V
ts	Start-up Time	No Load		_	20	_	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	MΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	—	Ω
T _{OTSD}	Thermal Shutdown Temperature	_			+160	_	
THYOTSD	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
		SOT89-5		_	47	_	



AP2112-2.5 Electrical Characteristics ($@V_{IN} = 3.5V$, $C_{IN} = 1.0\mu F$ (Ceramic), $C_{OUT} = 1.0\mu F$ (Ceramic), Typical $T_A = +25^{\circ}C$, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ons	Min	Тур	Мах	Unit
Vout	Output Voltage	V _{IN} = 3.5V, 1mA ≤ I ₀	$V_{IN} = 3.5V$, 1mA $\leq I_{OUT} \leq 30$ mA		2.5	V _{ОUТ} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	$V_{IN} = 3.5V,$ $V_{OUT} = 2.463V$ to 2.5	537V	600		_	mA
(ΔV _{OUT} /V _{OUT})/ΔI _{OUT}	Load Regulation	$V_{OUT} = 2.5V, V_{IN} = V$ 1mA $\leq I_{OUT} \leq 600mA$		-1	0.2	1	%/A
$(\Delta V_{OUT}/V_{OUT})/\Delta V_{IN}$	Line Regulation	$3.5V \le V_{IN} \le 6V, I_{OU}$	_T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	5	8	
Vdrop	Dropout Voltage	I _{OUT} = 300mA		_	125	200	mV
		I _{OUT} = 600mA		_	250	400	
lq	Quiescent Current	$V_{IN} = 3.5V$, $I_{OUT} = 0r$	nA	_	55	80	μA
I _{STD}	Standby Current	V_{IN} = 3.5V, V_{EN} in O	FF mode	_	0.01	1.0	μA
		Ripple 0.5Vp-p	f = 100Hz	_	65	_	
PSRR	Power Supply Rejection Ratio	V _{IN} = 3.5V, I _{OUT} = 100mA	f = 1KHz	_	65	_	dB
$(\Delta V_{OUT}/V_{OUT})/\Delta T$	Output Voltage Temperature Coefficient	I _{OUT} = 30mA T _A = -40°C to +85°C	:	_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	$V_{OUT} = 0V$		_	50	—	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	_	μV _{RMS}
VIH	V _{EN} High Voltage	Enable logic high, re	gulator on	1.5	_	6.0	
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0	_	0.4	V
ts	Start-up Time	No Load		_	20	—	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	MΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
TOTSD	Thermal Shutdown Temperature	_		_	+160	_	
THYOTSD	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
		SOT89-5		_	47	_	



AP2112-2.6 Electrical Characteristics ($@V_{IN} = 3.6V$, $C_{IN} = 1.0\mu F$ (Ceramic), $C_{OUT} = 1.0\mu F$ (Ceramic), Typical $T_A = +25^{\circ}C$, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ions	Min	Тур	Max	Unit
Vout	Output Voltage	$V_{IN} = 3.6V$, 1mA $\leq I_{OUT} \leq 30$ mA		V _{ОUT} *98.5%	2.6	V _{ОUT} *101.5%	V
IOUT(MAX)	Maximum Output Current	$V_{IN} = 3.6V,$ $V_{OUT} = 2.561V$ to 2.6	639V	600	_	_	mA
(ΔV _{OUT} /V _{OUT})/ΔI _{OUT}	Load Regulation	$V_{OUT} = 2.6V, V_{IN} = V$ 1mA $\leq I_{OUT} \leq 600$ mA		-1	0.2	1	%/A
$(\Delta V_{OUT}/V_{OUT})/\Delta V_{IN}$	Line Regulation	$3.6V \le V_{IN} \le 6V, I_{OU}$	_T = 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	5	8	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		_	125	200	mV
		I _{OUT} = 600mA		_	250	400	
lα	Quiescent Current	$V_{IN} = 3.6V$, $I_{OUT} = 0r$	nA	_	55	80	μA
I _{STD}	Standby Current	V_{IN} = 3.6V, V_{EN} in O	FF mode	_	0.01	1.0	μA
		Ripple 0.5Vp-p	f = 100Hz	_	65	_	
PSRR	Power Supply Rejection Ratio	V _{IN} = 3.6V, I _{OUT} = 100mA	f = 1kHz	_	65	_	dB
(ΔV _{OUT} /V _{OUT})/ΔT	Output Voltage Temperature Coefficient	I _{OUT} = 30mA T _A = -40°C to +85°C	;	_	±100	_	ppm/°C
ISHORT	Short Current Limit	$V_{OUT} = 0V$		—	50	—	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	—	μV _{RMS}
VIH	V _{EN} High Voltage	Enable logic high, re	gulator on	1.5	_	6.0	
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0	_	0.4	V
ts	Start-up Time	No Load		_	20	—	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	MΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	_	
THYOTSD	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	°C/W
		SOT89-5		_	47	_	



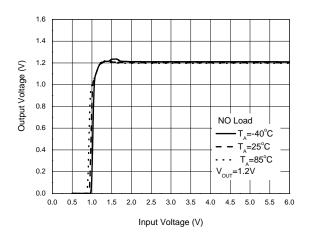
AP2112-3.3 Electrical Characteristics ($@V_{IN} = 4.3V$, $C_{IN} = 1.0\mu F$ (Ceramic), $C_{OUT} = 1.0\mu F$ (Ceramic), Typical $T_A = +25^{\circ}C$, unless otherwise specified (Note 6))

Symbol	Parameter	Conditi	ons	Min	Тур	Max	Unit
Vout	Output Voltage	$V_{IN} = 4.3V$, 1mA $\leq I_C$	ou⊤ ≤ 30mA	V _{OUT} *98.5%	3.3	V _{ОUT} *101.5%	V
I _{OUT(MAX)}	Maximum Output Current	V_{IN} = 4.3V, V_{OUT} = 3.251V to 3.350V		600	_	—	mA
$(\Delta V_{OUT}/V_{OUT})/\Delta I_{OUT}$	Load Regulation	$V_{IN} = 4.3V$, 1mA $\leq I_C$	_{0UT} ≤ 600mA	-1	0.2	1	%/A
(ΔVout/Vout)/ΔVin	Line Regulation	4.3V≤ V _{IN} ≤ 6V, I _{OUT}	= 30mA	-0.1	0.02	0.1	%/V
		I _{OUT} = 10mA		_	5	8	
V _{DROP}	Dropout Voltage	I _{OUT} = 300mA		_	125	200	mV
		I _{OUT} = 600mA		_	250	400	
Ι _Q	Quiescent Current	$V_{IN} = 4.3V$, $I_{OUT} = 0n$	nA	_	55	80	μA
ISTD	Standby Current	$V_{IN} = 4.3V, V_{EN}$ in O	FF mode	_	0.01	1.0	μA
		Ripple 0.5Vp-p	f = 100Hz	_	65	_	
PSRR	Power Supply Rejection Ratio	V _{IN} = 4.3V, I _{OUT} = 100mA	f = 1kHz	_	65	_	dB
(ΔVουτ/Vουτ)/ΔΤ	Output Voltage Temperature Coefficient	I _{OUT} = 30mA T _A = -40°C to +85°C		_	±100	_	ppm/°C
I _{SHORT}	Short Current Limit	V _{OUT} = 0V		—	50	—	mA
V _{NOISE}	RMS Output Noise	No Load, 10Hz ≤ f ≤	100kHz	_	50	—	μV _{RMS}
VIH	V _{EN} High Voltage	Enable logic high, re	gulator on	1.5	_	6.0	
VIL	V _{EN} Low Voltage	Enable logic low, reg	gulator off	0		0.4	V
t _S	Start-up Time	No Load		_	20	—	μs
R _{PD}	EN Pull Down Resistor	_		_	3.0	_	MΩ
R _{DCHG}	V _{OUT} Discharge Resistor	Set EN pin at Low		_	60	_	Ω
T _{OTSD}	Thermal Shutdown Temperature	_		_	+160	—	
T _{HYOTSD}	Thermal Shutdown Hysteresis	_		_	+25	_	°C
		SOT25		_	96	_	°C/W
θ _{JC}	Thermal Resistance (Junction to Case)	SO-8		_	75	_	
		SOT89-5		_	47	_	

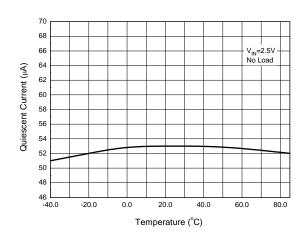


Performance Characteristics

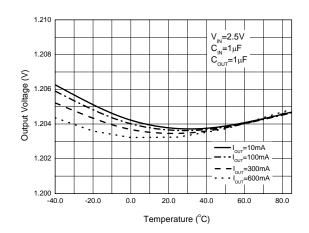
Output Voltage vs. Input Voltage



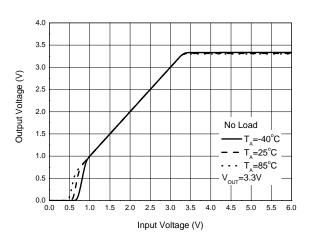
Quiescent Current vs. Temperature



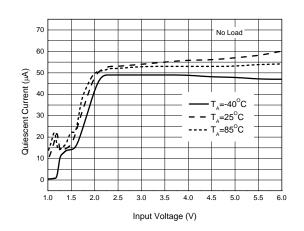
Output Voltage vs. Temperature



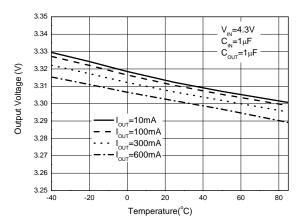
Output Voltage vs. Input Voltage



Quiescent Current vs. Input Voltage

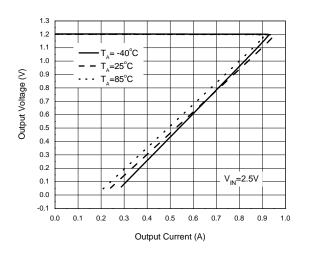


Output Voltage vs. Temperature



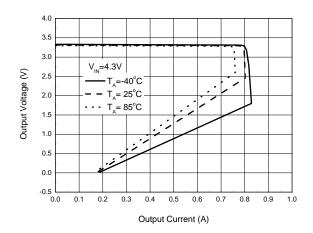


Performance Characteristics (Cont.)

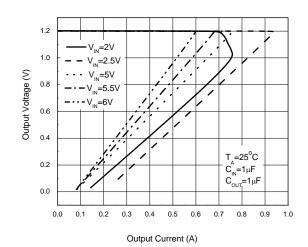


Output Voltage vs. Output Current

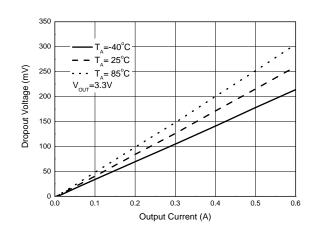
Output Voltage vs. Output Current



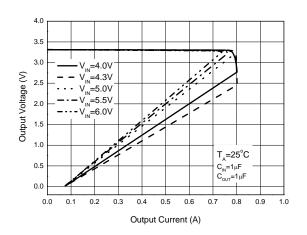
Output Voltage vs. Output Current



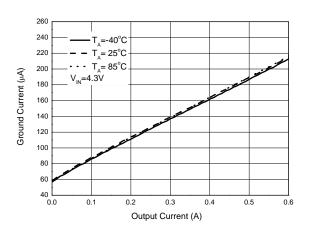
Dropout Voltage vs. Output Current



Output Voltage vs. Output Current



Ground Current vs. Output Current

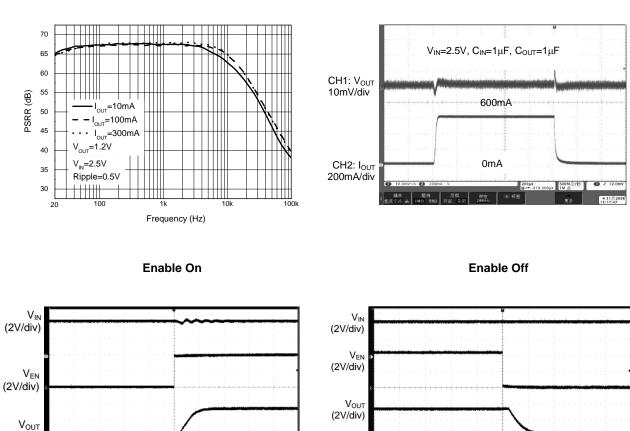


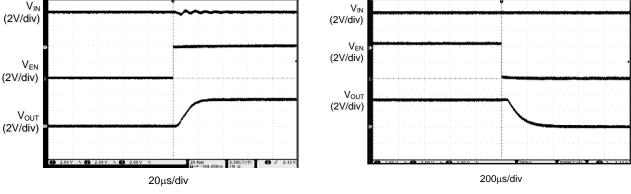


Performance Characteristics (Cont.)

PSRR vs. Frequency

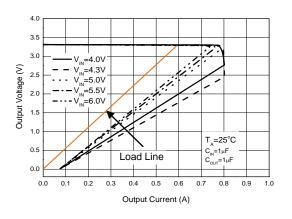
Load Transient





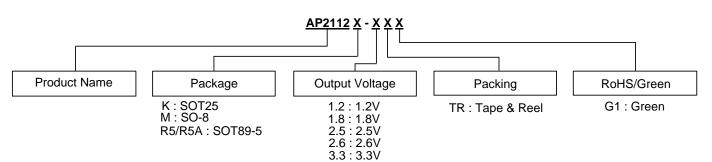
Application Note

In some unusual applications where a current load could be present at the output before the part is enabled the fold back current limiting may prevent the part from starting. Applications with multiple supplies or negative supplies need to be evaluated for this possibility. Product testing where a current source is applied before the part is enabled could be another area of concern. With a normal load as shown below there is no interference of the fold back current limiting circuit.





Ordering Information



Package	Temperature Range	Condition	Part Number	Marking ID	Packing
		1.2V	AP2112K-1.2TRG1	G3L	3000/7"/Tape & Reel
		1.8V	AP2112K-1.8TRG1	G3M	3000/7"/Tape & Reel
SOT25	-40 to +85°C	2.5V	AP2112K-2.5TRG1	G3N	3000/7"/Tape & Reel
		2.6V	AP2112K-2.6TRG1	G5N	3000/7"/Tape & Reel
		3.3V	AP2112K-3.3TRG1	G3P	3000/7"/Tape & Reel
		1.2V	AP2112M-1.2TRG1	2112M-1.2G1	4000/13"/Tape & Reel
		1.8V	AP2112M-1.8TRG1	2112M-1.8G1	4000/13"/Tape & Reel
SO-8	-40 to +85°C	2.5V	AP2112M-2.5TRG1	2112M-2.5G1	4000/13"/Tape & Reel
		2.6V	AP2112M-2.6TRG1	2112M-2.6G1	4000/13"/Tape & Reel
		3.3V	AP2112M-3.3TRG1	2112M-3.3G1	4000/13"/Tape & Reel
		1.2V(R5)	AP2112R5-1.2TRG1	G37D	1000/7"/Tape & Reel
		1.8V(R5)	AP2112R5-1.8TRG1	G37E	1000/7"/Tape & Reel
SOT89-5	-40 to +85°C	2.5V(R5)	AP2112R5-2.5TRG1	G37F	1000/7"/Tape & Reel
		2.6V(R5)	AP2112R5-2.6TRG1	G13F	1000/7"/Tape & Reel
		3.3V(R5)	AP2112R5-3.3TRG1	G37G	1000/7"/Tape & Reel
		1.2V(R5A)	AP2112R5A-1.2TRG1	G33C	1000/7"/Tape & Reel
		1.8V(R5A)	AP2112R5A-1.8TRG1	G33E	1000/7"/Tape & Reel
SOT89-5	-40 to +85°C	2.5V(R5A)	AP2112R5A-2.5TRG1	G28G	1000/7"/Tape & Reel
		2.6V(R5A)	AP2112R5A-2.6TRG1	G13E	1000/7"/Tape & Reel
		3.3V(R5A)	AP2112R5A-3.3TRG1	G28H	1000/7"/Tape & Reel



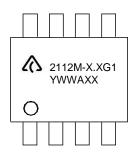
Marking Information

(1) SOT25



: Logo XXX : Marking ID (See Ordering Information)

(2) SO-8



First line: Logo and Marking ID Second line: Date Code Y: Year WW: Work Week of Molding A: Assembly House Code XX: 7th and 8th Digits of Batch Number

(3) SOT89-5



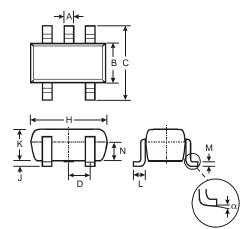
First Line: Logo and Marking ID Second line: Date Code Y: Year WW: Work Week of Molding A: Assembly House Code XX: 7th and 8th Digits of Batch Number



Package Outline Dimensions (Previously identified as SOT-23-5 for this product)

Please see http://www.diodes.com/package-outlines.html for the latest version.

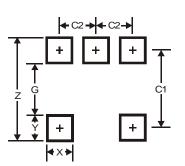




SOT25						
Dim	Min	Max	Тур			
Α	0.35	0.50	0.38			
в	1.50	1.70	1.60			
с	2.70	3.00	2.80			
D	-	-	0.95			
Η	2.90	3.10	3.00			
J	0.013	0.10	0.05			
K	1.00	1.30	1.10			
_	0.35	0.55	0.40			
Μ	0.10	0.20	0.15			
Ν	0.70	0.80	0.75			
α 0° 8° -						
All D	All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT25

Dimensions	Value
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95

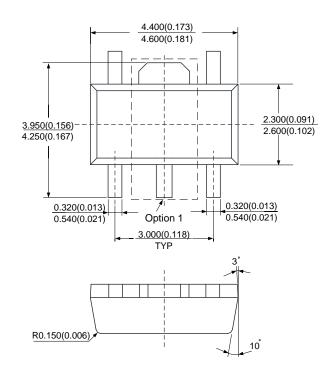
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

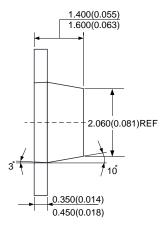
Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



Package Outline Dimensions (All dimensions in mm.) (Previously identified as SOT-89-5 for this product)

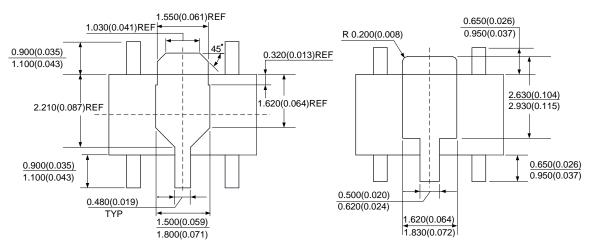
SOT89-5





Option 1

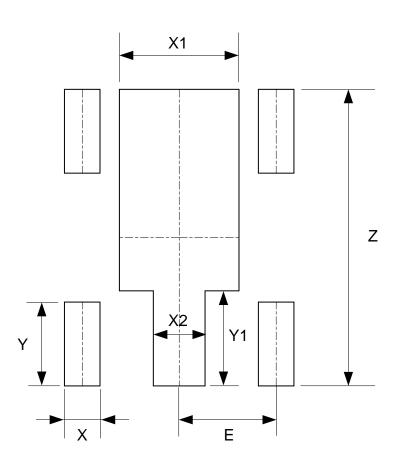






Suggested Pad Layout (Previously identified as SOT-89-5 for this product)

SOT89-5

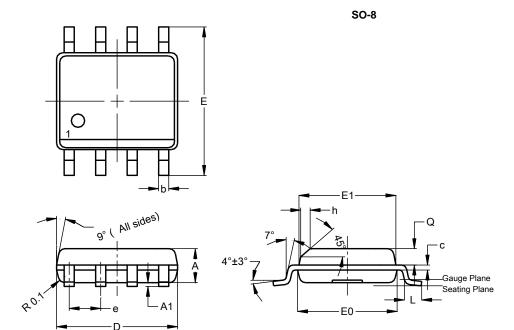


Dimensions	Z	Х	X1	X2	Y	Y1	E
Dimensions	(mm)/(inch)						
Value	4.600/0.181	0.550/0.022	1.850/0.073	0.800/0.031	1.300/0.051	1.475/0.058	1.500/0.059



Package Outline Dimensions (Previously identified as SOIC-8 for this product)

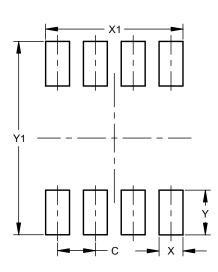
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8				
Dim	Min	Max	Тур	
Α	1.40	1.50	1.45	
A1	0.10	0.20	0.15	
b	0.30	0.50	0.40	
С	0.15	0.25	0.20	
D	4.85	4.95	4.90	
Е	5.90	6.10	6.00	
E1	3.80	3.90	3.85	
E0	3.85	3.95	3.90	
е			1.27	
h	-		0.35	
L	0.62	0.82	0.72	
Q	0.60	0.70	0.65	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)	
С	1.27	
Х	0.802	
X1	4.612	
Y	1.505	
Y1	6.50	

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

SO-8



AP2112

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